



PATENT  
0171-0808P

IN THE U.S. PATENT AND TRADEMARK OFFICE

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Applicant: Syuuichi AZECHI et al. Conf.: 3484  
Appl. No.: 10/035,213 Group: 1712  
Filed: January 4, 2002 Examiner: Michael J. Feely  
For: SILICONE RUBBER ADHESIVE  
COMPOSITION AND INTEGRALLY MOLDED  
ARTICLE OF SILICONE RUBBER AND  
THERMOPLASTIC RESIN

LETTER

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 11, 2003

Sir:

A review of the file of the undersigned indicates that two documents may not have been received by the PTO even though the PTO has acknowledged receipt thereof.

These documents are attached hereto with apologies for any inconvenience.

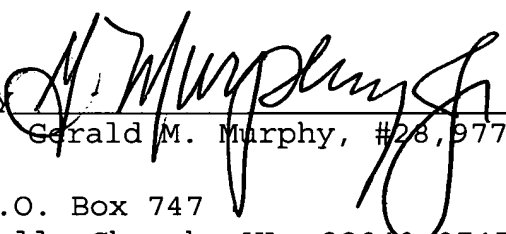
Should there be any outstanding matters that need to be resolved in the present application, the Examiner is respectfully requested to contact David R. Murphy (Reg. No. 22,751) at the telephone number of the undersigned below,

to conduct an interview in an effort to expedite  
prosecution in connection with the present application.

Respectfully submitted,

BIRCH, STEWART, KOLASCH & BIRCH, LLP

By

  
Gerald M. Murphy, #28,977

*om*  
GMM/DRM/jmb  
0171-0808P

P.O. Box 747  
Falls Church, VA 22048-0747  
(703) 205-8000

- Attachment(s):
1. Declaration of Syuuichi AZECHI et al.  
dated May 30, 2003 (4 pages)
  2. Certified Translation of JP 2001-000536

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APPLICANT: Syuuichi AZECHI et al.  
SERIAL NO.: 10/035,213  
FILED: January 4, 2002  
FOR: Silicone Rubber Adhesive Composition  
and Integrally Molded Article of  
Silicone Rubber and Thermoplastic Resin  
GROUP: 1712  
EXAMINER: FEELY, MICHAEL J

D E C L A R A T I O N

Honorable Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Sir,

I, Syuuichi AZECHI, resident of c/o  
Silicone-Electronics Materials Research Center,  
Shin-Etsu Chemical Co., Ltd., 1-10, Oaza Hitomi,  
Matsuida-machi, Usui-gun, Gunma-ken, Japan do hereby  
declare that:

1. I was graduated from Master Course of Department of Engineering, Gunma University, Japan in March 1988. Since April 1988, I have been employed by Shin-Etsu Chemical Co., Ltd., the assignee of the above-identified application. I have been engaged in research and development relating to silicones in the laboratory of the Company.

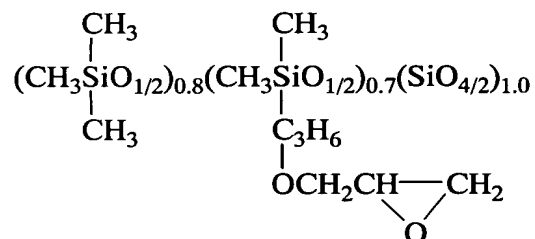
2. I am one of the named inventors of the above-identified application and hence, am familiar with the subject matter disclosed in said application.

3. In order to show the feature of the present invention, I conducted the following experiments.

## [Experiment]

### Comparison

Example 1 described in the specification of the above-identified application was repeated except that 5 parts by weight of an epoxy group-containing MQ resin:



disclosed in Preparation Example 1 of Morita '075 was used instead of tackifier I. The adhesion examined in the same manner as in the specification of the above-identified application. The results are shown in the following table. As is evident from the results, the effect of the present invention is not attained even if the above MQ resin is used.

Adhesion	Resin	PC	No
		PBT	No
		PMMA	No
		PPS	No
		PA66	No
		PPA	No
	Metal (mold)	Cr-plated	Bonded

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

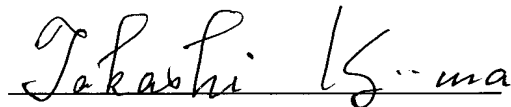
Dated this 30<sup>th</sup> day of May, 2003

Syunchi Azechi

C E R T I F I C A T I O N

I, Takashi KOJIMA of Ginza Ohtsuka Bldg., 2F, 16-12, Ginza 2-chome, Chuo-ku, Tokyo, Japan, hereby certify that I am the translator of the accompanying certified official copy of the documents in respect of an application for a patent filed in Japan on the 5th of January, 2001 and of the official certificate attached thereto, and certify that the following is a true and correct translation to the best of my knowledge and belief.

Dated this 5th day of June, 2003

  
Takashi KOJIMA